

Technical Bulletin



Solder plus Support

NC217 No Clean Flux Gel

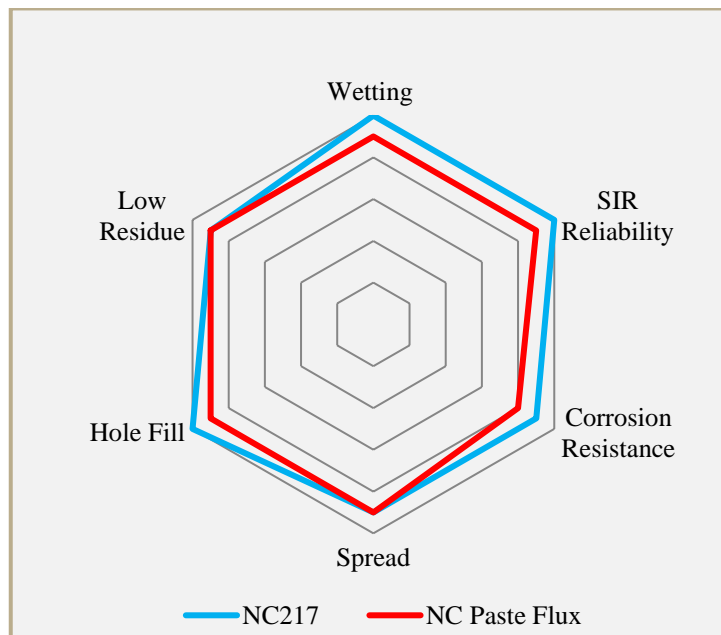
DESCRIPTION

NC217 Gel Flux is specifically designed for touch-up and repair work. NC217 has a gel-like consistency minimizing spreading during rework and improving heat transfer from the soldering iron tip or hot air source. NC217 provides a much wider process window than liquid flux and lower residue than tacky flux. Gel flux spreading beyond the heated rework area, once dry, passes J-STD-004A/B/C unheated. NC217 dries within one hour of use with or without heat and is tack-free after four hours.

FEATURES AND BENEFITS

- Formulated for Rework and Repair
- Ideal for BGA – Wide Process Window/Low Voiding
- Tin-Lead and Lead-Free Compatible
- Electrically Safe Unheated
- ROL0 per IPC J-STD-004

CHARACTERISTICS

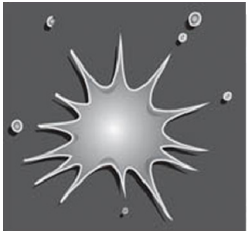


STORAGE & SHELF LIFE

NC217 has a sealed shelf life of six (6) months when stored at room temperature. Do not store near fire or flame. Keep away from sunlight as it may degrade product. NC217 is shipped ready-to-use, no mixing necessary. Do not mix used and unused chemicals in the same container. Reseal any opened containers. After opening, gel flux shelf life is environment and application dependent.

PARAMETER	TIME	TEMPERATURE
Sealed Unrefrigerated Shelf Life	6 Months	Room Temperature

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APPLICATION

NC217 is formulated for application via dispense needle, brush, or a cotton swab. NC217 is ready to use directly from its container, no thinning required

PROCESS GUIDELINES

NC217 should be applied sparingly to solderable surfaces prior to heat application. NC217 can be used with soldering irons, hot air pencils, BGA rework stations or micro ovens.

CLEANING

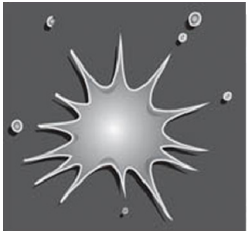
NC217 Gel Flux residues do not require removal. However, residues can be easily cleaned if necessary using common flux removers. Isopropyl alcohol (IPA) is not recommended. Contact AIM for additional cleaning information.

HEALTH & SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying Safety Data Sheet for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.

TEST DATA SUMMARY

NAME	TEST METHOD	RESULTS	
IPC Flux Classification	J-STD-004	ROLO	
NAME	TEST METHOD	RESULTS	IMAGE
Copper Mirror	J-STD-004B 3.4.1.1 IPC-TM-650 2.3.32	LOW	
Corrosion	J-STD-004B 3.4.1.2 IPC-TM-650 2.6.15	PASS	
Quantitative Halides	J-STD-004B 3.4.1.3 IPC-TM-650 2.3.28.1	≤ 0.0	
Qualitative Halides, Silver Chromate	J-STD-004B 3.5.1.1 IPC-TM-650 2.3.33	PASS	
Qualitative Halides, Fluoride Spot	J-STD-004B 3.5.1.2 IPC-TM-650 2.3.35.1	No Fluoride	



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NAME	TEST METHOD	RESULTS	IMAGE
Surface Insulation Resistance	J-STD-004B 3.4.1.4 IPC-TM-650 2.6.3.7	PASS	
	J-STD-004 3.4.1.4 IPC-TM-650 2.6.3.3	PASS	
Acid Value Determination	J-STD-004B 3.4.2.2 IPC-TM-650 2.3.13	167 mg KOH per gram flux Typical	
Flux Specific Gravity Determination	J-STD-004B 3.4.2.3 ASTM D-1298	≈ 0.9872	
Viscosity	J-STD-004B 3.4.2.4 IPC-TM-650 2.4.34	100 – 400 kcps	
Visual	J-STD-004B 3.4.2.5	Dark Yellow	
Wetting	J-STD-005A 3.9 IPC-TM-650 2.4.45	PASS	

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